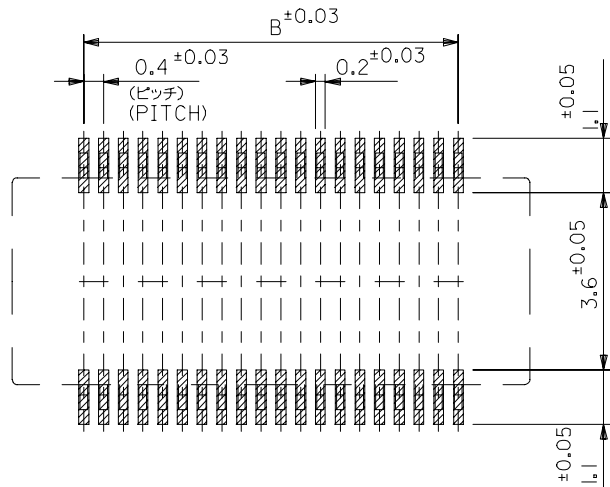


18.52	17.6	20.5	54796-0903	90
16.52	15.6	18.5	54796-0803	80
12.52	11.6	14.5	54796-0603	60
10.52	9.6	12.5	54796-0503	50
8.52	7.6	10.5	54796-0403	40
6.92	6.0	8.9	54796-0323	32
C	B	A	MATERIAL NO.	極数 CK+

材料 MATERIAL	
注記参照 SEE NOTES	
仕上げ FINISH	#
適用電線範囲 WIRE RANGE	#
被覆外径 INS. RANGE	#

REVISED EC NO: J2005-2961 2005/04/06 DRAWN: NABEI 2005/04/07 CHKD: KTOJO 2005/04/12 APPR: NUKITA 2005/04/12	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 54796-***3
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE 0.4 B-TO-B CONN REC ASSY [NI BARRIER] (HGT=1.5) -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	T. ITO	'03/07/18		
	30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED	
ANGULAR	±3 °	T. YAMAGUCHI	'03/07/18			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY T. YAMAGUCHI DATE '03/07/18		MATERIAL NO. SEE CHART	DOCUMENT NO. SD-54796-005	SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



参考基板レイアウト (マウント面)
P.C. BOARD PATTERN DIMENSION. (REFERENCE)
(MOUNTING AREA)

注記 NOTES:

1. 使用材料 MATERIAL
ハウジング: 液晶ポリマー (LCP) ガラス充填 UL94V-0 (黒)
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)
UL94V-0 (COLOR: BLACK)
ターミナル: リン青銅 (t=0.15)
TERMINAL: PHOSPHOR BRONZE (t=0.15)
 2. メッキ仕様 PLATING
ターミナル TERMINAL
金メッキ 0.25マイクロメートル以上 (コンタクト部)
GOLD 0.25MICROMETER MINIMUM (CONTACT AREA)
金メッキ 0.4マイクロメートル以下 (テール部)
GOLD 0.4MICROMETER MAXIMUM (TAIL AREA)
下地メッキ: ニッケルメッキ1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5MICROMETER MINIMUM
*コンタクト部とテール部はニッケルメッキによって分断されている金メッキです。
DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT
AND THE TAIL PART BY THE NICKEL PLATING.
- △ (全極数/2) = 偶数の場合に適用。
APPLY FOR (CIRCUIT/2)=EVEN.
4. 嵌合相手: 55622 シリーズ
MATE WITH: 55622 SERIES
 5. テール平坦度は、0.08以下
TAIL COPLANARITY TO BE 0.08MAXIMUM

MODEL NO. 54796-***3

REVISED EC NO: J2005-2961 DRAWN: NABEI 2005/04/06 CHKD: KTOJO 2005/04/07 APPR: NUKITA 2005/04/12 DESCRIPTION REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/07/18	TITLE 0.4 B-TO-B CONN REC ASSY [NI BARRIER] (HGT=1.5) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/07/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/07/18	DOCUMENT NO. SD-54796-005		
	ANGULAR ±3 °		MATERIAL NO. SEE CHART		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			